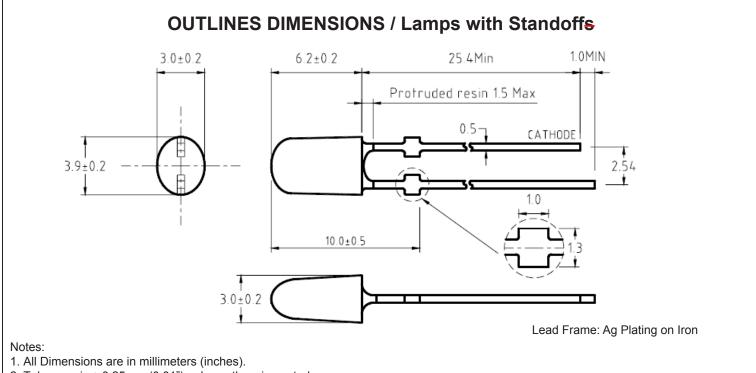


SPECIFICATIONS

CLV43GT2DS-110



2. Tolerance is \pm 0.25mm (0.01") unless otherwise noted.

3. Specifications are subject to change without notice.

Luminous Intensity Bin Table			
IF=20mA			
Rank	Min	Max	
Name	(mcd)	(mcd)	
R	1500	1900	
S	1900	2500	
Т	2500	3200	

* Tolerance for each bin limit is ±15%

Color Bin Table			
IF=20mA			
Rank	Min	Max	
Name	(mcd)	(mcd)	
1	515	520	
2	520	525	
3	525	530	
4	530	535	

* Tolerance for each bin limit is ± 1nm

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CLV43GT2DS-110	InGaN	Pure-Green	Epoxy Resin	110/40°





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Power Dissipation	PD	114	mW	
Pulse Current Forward Current	I _{FP}	100	mA	
Continuous Forward Current	lF	30	mA	
Reverse Voltage	V _R	5.0	V	
Operating Temperature Range	T _{OPR}	-30 ~ +85	٥C	
Storage Temperature Range	T _{STG}	-40 ~ +100	٥C	
I_{FP} = Pulse Width \leq 10 ms, Duty Ratio \leq 1/10. Soldering Condition: 260 °C/ 5sec				

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

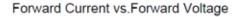
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	I⊧= 20mA	1500	2000	-	mcd
Forward Voltage	VF	I⊧= 20mA	-	3.2	3.8	V
Reverse Leakage Current	I _R	$V_R = 5V$	-	-	50	μA
Viewing Angle	201/2	I⊧= 20mA	-	110/40°	-	deg.
Peak Wavelength	λP	I⊧= 20mA	-	518	-	nm
Dominant Wavelength	λD	I _F = 20mA	515	525	535	nm
Spectral Line half-width	Δλ	I⊧ = 20mA	-	30	-	nm

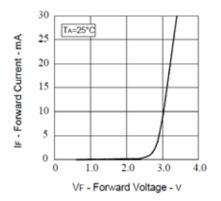
*Tolerance of viewing angle: -10 / +5 deg.



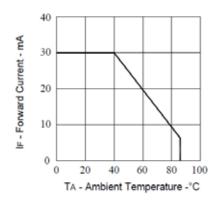


OPTICAL CHARACTERISTIC CURVES

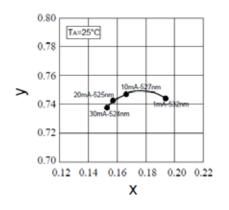




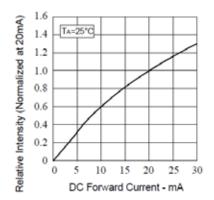
Forward Current vs.Ambient Temperature



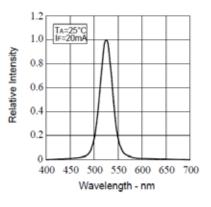
Forward Current vs.Chromaticity Coordinate



Relative Intensity vs.Forward Current



Relative Intensity vs.Wavelength







SOLDERING CONDITIONS – LAMP TYPE LED

- * Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- * Recommended soldering conditions

Dip Soldering				
Pre-Heat	100 °C Max			
Pre-Heat Time	60 Second Max			
Solder Bath Temperature	260 °C Max			
Dippng Time	5 Second Max			
Dipping Position	No lower than 3mm from the base of the epoxy			

Hand Soldering			
	3mm Series	Others	
Temperature Soldering Time Position	300 °C Max 3 Second Max No closer than 3mm from the base of the epoxy	350 °C Max 3 Second Max No closer than 3mm from the base of the epoxy	

- * Do not apply any stress to the lead. Particularly when heated.
- * The LED must not be repositioned after soldering.
- * After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- * Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- * When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- * Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.

